Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(currently amended) A method to dissipate heat generated ~~from a source~~ by a coil located within a micro-structure, that is on a substrate, comprising:

forming a thermally conductive pedestal that extends upwards from said substrate; and

forming a layer of thermally conductive material that ~~contacts~~ connects said pedestal to ~~and extends therefrom as far as~~ said ~~heat source~~ coil.

2.(currently amended) The method of claim 1 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between ~~about~~ 100 and 400 W/m.K.

3. (currently amended) The method of claim 1 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, iridium, and ~~their mutual~~ all alloys limited to these elements.

4. (currently amended) The method of claim 1 wherein said layer of thermally conductive material has a thickness between ~~about~~ 1 and 2.5 microns.

5. (currently amended) The method of claim 1 wherein said pedestal has a cross-sectional area that is between ~~about~~ 10,000 and 15,000 sq. microns.

6. (currently amended) The method of claim 1 wherein said ~~source~~ coil generates heat at a rate between ~~about~~ 4 and 15 milliwatts.

7-24. Canceled

25. (currently amended) A heat extractor for a micro-structure that includes a ~~heat source~~ coil and a substrate, comprising:

a thermally conductive pedestal that extends upwards from said substrate; and

a layer of thermally conductive material that ~~contacts~~ connects said pedestal to ~~and extends therefrom as far as~~ said ~~heat source~~ coil.

26. (currently amended) The heat extractor described in claim 25 wherein said layer of thermally conductive material and said conductive pedestal have a thermal conductivity between ~~about~~ 100 and 400 W/m.K.

27. (currently amended) The heat extractor described in claim 25 wherein said layer of thermally conductive material is selected from the group consisting of copper, tungsten, molybdenum, silicon, ruthenium, rhodium, iridium, and ~~their mutual~~ all alloys limited to these elements.

28. (currently amended) The heat extractor described in claim 25 wherein said layer of thermally conductive material has a thickness between ~~about~~ 1 and 2.5 microns.

29. (currently amended) The heat extractor described in claim 25 wherein said pedestal has a cross-sectional area that is between ~~about~~ 10,000 and 15,00 sq. microns.

27-39. Canceled